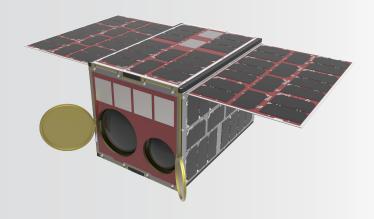


# **12U PLATFORM**

### MAIN FFATURES\*

- In-house developed structure and subsystems
- 5-year design lifetime in LEO
- Population by ESA-qualified hand soldering operators
- Double redundancy in all subsystems
- Single-point failure tolerant design
- 32% higher payload power availability\*
- Integration time reduced by 55%\*
- Redundant CAN and MLVDS buses (OBC)
- Maximized payload volume due to flexible positioning



\*Platform developed under the framework of RADCUBE mission founded by ESA

### SUMMARY

C3S's main strength in the small satellite industry is that our engineering team devoted great attention to thermal design during the development of our platform. Therefore, the structure is optimized for high dissipation density and thermo-elasticity, both payload and platform wise. Along unprecedentedly high payload power availability our bus offers great flexibility regarding the shape and positioning of the payload. Our devoted team will be at your service from mission planning throughout the operation of the entire mission, until deorbiting.

### **SERVICES**

- Launch management
- Testing
- Remote testing facility using flatsat
- Mission planning
- Payload design & MAIT from TRL 4
- Mission Operation Center based data collection for one month or longer upon request /extension available

### **USE CASES**

- Earth observation
- loT
- IOD

- Space weather monitoring
- Cyber security

## **TESTS PERFORMED\***

- ✓ SEE radiation test (in anechoic chamber)
- ✓ TID test
- √ Vibration test
- ✓ TVAC test (thermal cycling & thermal balance tests, performed in thermal-vacuum chamber)
- ✓ Burn-in test
- √ Functional test
- ✓ RF test
- ✓ Autocompatibility test
- ✓ Mechanical properties inspection

\* Test plan and test reports approved by ESA

<sup>\*\*</sup> Than market average







### **SPECIFICATION**

### PI ATFORM

	PLATFORM		
	Property	Value/Options	Notes
	Mass	18 kg	Payload excluded
	Dimensions	226.3 x 226.3 x 366 mm	12U size
	Subsystem mechanical interfaces	Card Guide, Box-in-a-box	
	Subsystem interconnection	Rigid backplane with nano-D and micro-D connectors	
	Redundancy	Subsystem level cold redundancy	
	Lifetime	5-year design lifetime in LEO	
	Operating temperature range	-40 °C +80 °C	Except battery pack (0°C+50 °C)
	Platform average power consumption	7.9 W	Mission dependent
	Platform peak power consumption	25 W	Mission dependent
	Maximum incoming solar power	65 W	12-20 independent MPPT channels
	Battery capacity	Up to 190 Wh	Depending on battery pack
	Power Buses	3.3 V, 5.0 V, 9.9 V – 12.6 V	
		2 x CAN bus	Cold-redundant pair
	Command bus, Data bus	2 x M-LVDS	Cold-redundant pair to COM
		2 x M-LVDS	Cold-redundant pair to PAY
	On-Board computer CPU Core	32bit ARM Cortex-M7	
	On-Board clock frequency	Up to 300 MHz	
	Mass storage capacity	16 GByte eMMC	
		16 MByte MRAM	Radiation resistant
	TX/RX Frequency Band	399-401 MHz	Professional Band
	Maximum transmit power	30 dBm	1 W
	Symbol rate uplink	1.25-150 kbps	
	Symbol rate downlink	5-150 kbps	
	Modulation	OOK/FSK/GFSK	

Continues on page 3/3



TITLE
COMPANY
ADDRESS

C3S PLATFORM DATA SHEET
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WWW.C3S.HU•SALES@C3S.HU•+36-21-200-5160

# 12U Platform/Specification

Knowledge accuracy	0.00833°	
Pointing accuracy	<<1°	

### PAYLOAD ALLOWANCE

Property	Value/Options	Notes
Volume	12.3 - 13.1 U	Depending on payload positioning
Dimensions within Z-frame	216.2 x 216.2 x 235 mm + 112.8 x 216.2 x 94 mm	Can be extended with up to 800,000 mm <sup>3</sup>
Average power (average during 1 orbit)	Up to 30W	Power available for the payload, depending on solar panel type
Peak Power	Up to 165W	Power available for the payload, depending on solar panel type
Communication interface	CAN 2.0B, M-LVDS	